

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC100N03MS G	**Issued**	25. January 2018
MA#	MA001823642		
Package	PG-TDSON-8-14	**Weight***	118.56 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.709	0.60	0.60	5979	5979
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82	
	non noble metal	zinc	7440-66-6	0.039	0.03		328	
	non noble metal	iron	7439-89-6	0.778	0.66		6562	
	non noble metal	copper	7440-50-8	31.590	26.64	27.34	266448	273420
wire	non noble metal	copper	7440-50-8	0.058	0.05	0.05	486	486
encapsulation	organic material	carbon black	1333-86-4	0.242	0.20		2038	
	plastics	epoxy resin	-	7.489	6.32		63170	
	inorganic material	silicondioxide	60676-86-0	40.588	34.25	40.77	342341	407549
leadfinish	non noble metal	tin	7440-31-5	1.243	1.05	1.05	10481	10481
plating	noble metal	silver	7440-22-4	0.037	0.03	0.03	316	316
solder	non noble metal	tin	7440-31-5	0.021	0.02		176	
	noble metal	silver	7440-22-4	0.026	0.02		220	
	non noble metal	lead	7439-92-1	0.996	0.84	0.88	8403	8799
heatspreader	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	zinc	7440-66-6	0.021	0.02		180	
	non noble metal	iron	7439-89-6	0.428	0.36		3606	
	non noble metal	copper	7440-50-8	17.360	14.64	15.02	146423	150254
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		43	
	non noble metal	iron	7439-89-6	0.017	0.01		143	
	non noble metal	copper	7440-50-8	16.898	14.25	14.26	142530	142716
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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